| L Number | Hits | Search Text | DB | Time stamp |
|---|---|---|---|---|
| 1 | 2552477 | semiconductor chip die flipchip (flip adj chip) ic (integrated adj circuit) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/27 19:44 |
| 2 | 8128983 | 1with (through hope via) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/27 19:43 |
| 3 | 428874 | (semiconductor chip die flipchip (flip adj chip) ic (integrated adj circuit)) with (through hope via) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/27 19:44 |
| 4 | 159597 | (wiring) with (substrate board carrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/27 19:44 |
| 5 | 14968 | ((semiconductor chip die flipchip (flip adj chip) ic (integrated adj circuit)) with (through hope via)) same ((wiring) with (substrate board carrier)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/27 19:44 |
| 6 | 703 | (flipchip (flip adj chip)) same (((semiconductor chip die flipchip (flip adj chip) ic (integrated adj circuit)) with (through hope via)) same ((wiring) with (substrate board carrier))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/27 19:46 |
| 7 | 417 | ((flipchip (flip adj chip)) same (((semiconductor chip die flipchip (flip adj chip) ic (integrated adj circuit)) with (through hope via)) same ((wiring) with (substrate board carrier)))) and (package packaging packaged) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/27 19:46 |

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